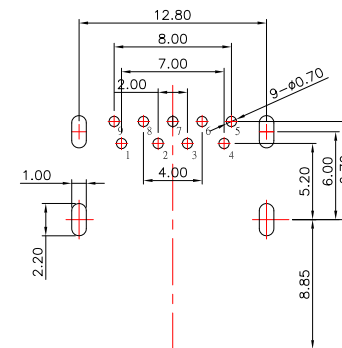
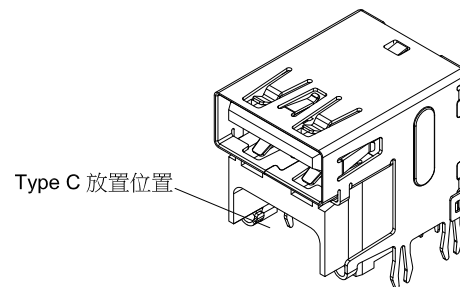
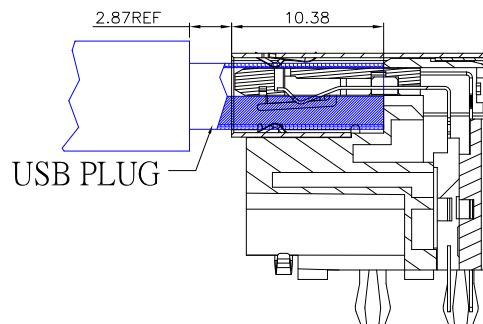
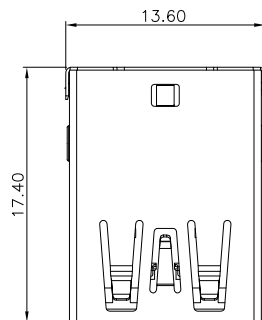
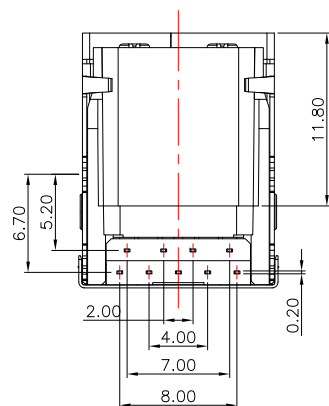
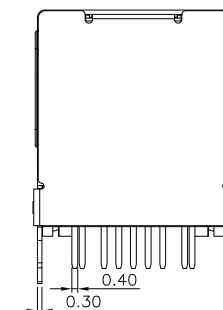
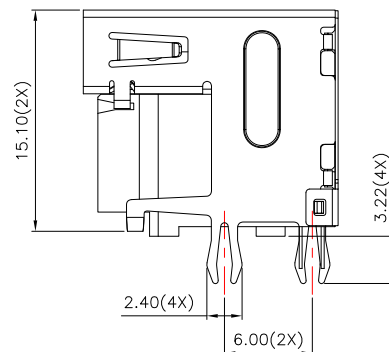
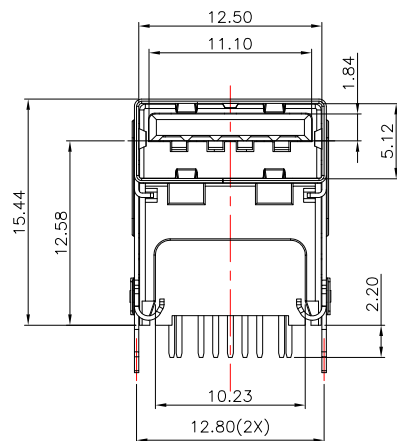




RECOMMENDED PCB LAYOUT



SUA-110H13-30xx-S277

鍍層厚度:	COLOR:
Blank: 1u"	BLUE: Blank
2: 15u"	Black: B
3: 30u"	Red: R

Contact Number	Signal Name
PIN1	VBUS
PIN2	D-
PIN3	D+
PIN4	GND
PIN5	StdA_SSRX-
PIN6	StdA_SSRX+
PIN7	GND_DRAIN
PIN8	StdA_SSTX-
PIN9	StdA_SSTX+
Shell	Shield

NOTE:

1.MATERIAL:

1.1 Housing: PA66

1.2 Contact: PHOSPHOR BRONZE

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.8 A

3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 500V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -40℃ ~ +85℃

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N



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CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 11/26/21
DATE: 11/26/21
DATE: 11/26/21

MAT'L
FINISH
SCALE: 1 : 1
SHEET NO. 1 of 1

TITLE: CONNECTOR
MODLE: USB AF DIP 架高 CH=12.58mm
DWG NO. SUA-110H13-30xx-S277
PART NO. SUA-110H13-30xx-S277

SIZE: A4
VER: R1

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增產品說明和更新材質	Jack	112621